



ASE GROUP



日月光半導體 2017第二季法人說明會

2017年7月28日

Safe Harbor Notice



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the uncertainties as to whether we can complete the share exchange contemplated by a joint share exchange agreement between Siliconware Precision Industries Co., Ltd. and us; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2016 Annual Report on Form 20-F filed on April 21, 2017.



2017 日月光集團上半年營運狀況



營收和獲利:

Q2 營收 US\$2.188bn, +3% QoQ/+13% YoY

Q2 淨利US\$260mn

上半年 營收 US\$4.321bn, +13% YoY

上半年半導體產業情況:

庫存水準正常

下半年預期:

需求穩定、審慎樂觀

ASE-SPIL Transaction Update



日月光及矽品共同轉換股份協議最新消息

- 台灣公平交易委員會已於2016年11月16日核准通過日月光與矽品結合案。
- 日月光於2017年5月16日收到美國聯邦貿易委員會之正式確認函，表示就本結合案所展開之非公開調查程序已告終止，且美國聯邦貿易委員會目前亦認為無需採取任何後續作為。
- 日月光與矽品於2016年8月25日向中國商務部遞交文件，並經過第一、二、三階段審查。鑑於商務部尚需更多時間審查本結合案，本公司遂遞件向商務部撤回原申請並再行遞件申請進行本結合案（下稱「再申請案」）。本公司於2017年6月6日分別接獲商務部准予本公司撤回原申請以及就再申請案准予立案之通知。日月光與矽品將持續依共同轉換股份協議約定以及相關法令規定，推動本結合案之進行。



附錄一：匯率影響



- 台幣匯率相對美金升值對於日月光今年第二季與上半年以新台幣計價之營收與獲利率造成不利影響。

Foreign Exchange Rate (USD/NTD) in 2Q17 & 1H17								
USD/NTD			2Q17 USD/NTD		USD/NTD		1H17 USD/NTD	
2Q17	1Q17	2Q16	QoQ	YoY	1H17	1H16		YoY
30.18	31.20	32.40	-3.3%	-6.8%	30.68	32.73		-6.2%

F/X Impact on 2Q17 GM (percentage points)		
QoQ (GM impact in 2Q17, -3.3% USD/NTD vs. 1Q17)	Group	-1.0
	IC ATM	-1.4
	EMS	-0.4
YoY (GM impact in 2Q17, -6.8% USD/NTD vs. 2Q16)	Group	-2.1
	IC ATM	-2.9
	EMS	-0.8

Revenues Growth		2Q17 QoQ	2Q17 YoY	1H17 YoY
Group	In USD	3%	13%	13%
IC ATM		5%	9%	12%
EMS		-0%	22%	24%
Group	In NTD	-1%	5%	6%
IC ATM		2%	1%	5%
EMS		-4%	14%	16%

附錄二： 投資獲利對於第二季獲利與獲利率之影響

- 不動產相關之投資獲利在第二季造成額外之分紅費用與所得稅費用認列。此分紅費用分別認列於第二季之銷貨成本與營業費用。
- 此投資獲利於第二季所貢獻的獲利淨影響數為新台幣每股0.48元。上述之分紅費用對於第二季日月光集團與半導體封裝測試業務之營業利益率所產生之不利影響數分別為0.6與1個百分點。

2Q17	NT\$bn			
Investment gain in 2Q17	5.6			
Tax expense incurred	-1.4			
After tax contribution	4.2			
Total bonus expense incurred from investment gain	-0.38	Bonus expense impact on margin (percentage points)		
			Group	IC ATM
<i>Bonus expense in Cost of Goods Sold</i>	-0.13	GM	-0.2	-0.3
<i>Bonus expense in Operating Expense</i>	-0.25	OPM	-0.6	-1.0
Net impact on earnings	3.9			
Net impact on 2Q17 basic EPS (NT\$)	0.48			

合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2017	%	Q1 / 2017	%	季變化
營業收入淨額:					
封裝	30,494	46.2%	29,806	44.8%	2%
測試	6,350	9.6%	6,365	9.6%	0%
材料直接銷售	928	1.4%	892	1.3%	4%
電子代工服務	28,210	42.7%	29,355	44.1%	-4%
其它	44	0.1%	133	0.2%	-67%
營業收入淨額合計	66,026	100.0%	66,551	100.0%	-1%
營業毛利	12,116	18.4%	11,975	18.0%	1%
營業淨利 (淨損)	5,219	7.9%	5,225	7.9%	0%
稅前淨利 (淨損)	11,390	17.3%	3,845	5.8%	196%
所得稅利益 (費用)	(3,207)	-4.9%	(886)	-1.3%	
非控制權益	(336)	-0.5%	(400)	-0.6%	
歸屬於本公司業主之淨利	7,847	11.9%	2,559	3.8%	207%
基本每股盈餘 (新台幣元)	0.97		0.33		194%
稀釋每股盈餘 (新台幣元)	0.89		0.29		207%
EBITDA	19,085	28.9%	11,764	17.7%	62%



合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2017	%	Q2 / 2016	%	年變化
營業收入淨額:					
封裝	30,494	46.2%	30,178	48.2%	1%
測試	6,350	9.6%	6,503	10.4%	-2%
材料直接銷售	928	1.4%	759	1.2%	22%
電子代工服務	28,210	42.7%	24,845	39.7%	14%
其它	44	0.1%	316	0.5%	-86%
營業收入淨額合計	66,026	100.0%	62,601	100.0%	5%
營業毛利	12,116	18.4%	12,254	19.6%	-1%
營業淨利 (淨損)	5,219	7.9%	5,889	9.4%	-11%
稅前淨利 (淨損)	11,390	17.3%	6,080	9.7%	87%
所得稅利益 (費用)	(3,207)	-4.9%	(1,523)	-2.4%	
非控制權益	(336)	-0.5%	(255)	-0.4%	
歸屬於本公司業主之淨利	7,847	11.9%	4,302	6.9%	82%
基本每股盈餘 (新台幣元)	0.97		0.56		73%
稀釋每股盈餘 (新台幣元)	0.89		0.47		89%
EBITDA	19,085	28.9%	13,977	22.3%	37%



綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2017	%	Q1 / 2017	%	季變化
營業收入淨額:					
封裝	31,718	81.2%	31,061	80.9%	2%
測試	6,350	16.3%	6,365	16.6%	0%
材料直接銷售	960	2.5%	935	2.4%	3%
其它	20	0.1%	24	0.1%	-17%
營業收入淨額合計	39,048	100.0%	38,385	100.0%	2%
營業毛利	9,027	23.1%	8,833	23.0%	2%
營業淨利 (淨損)	4,102	10.5%	3,983	10.4%	3%
稅前淨利 (淨損)	9,462	24.2%	3,207	8.4%	195%
所得稅利益 (費用)	(1,541)	-3.9%	(570)	-1.5%	
非控制權益	(74)	-0.2%	(78)	-0.2%	
歸屬於本公司業主之淨利	7,847	20.1%	2,559	6.7%	207%
EBITDA	11,522	29.5%	9,800	25.5%	18%



綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2017	%	Q2 / 2016	%	年變化
營業收入淨額:					
封裝	31,718	81.2%	31,180	81.0%	2%
測試	6,350	16.3%	6,502	16.9%	-2%
材料直接銷售	960	2.5%	801	2.1%	20%
其它	20	0.1%	21	0.1%	-5%
營業收入淨額合計	39,048	100.0%	38,504	100.0%	1%
營業毛利	9,027	23.1%	9,559	24.8%	-6%
營業淨利 (淨損)	4,102	10.5%	4,915	12.8%	-17%
稅前淨利 (淨損)	9,462	24.2%	5,608	14.6%	69%
所得稅利益 (費用)	(1,541)	-3.9%	(1,266)	-3.3%	
非控制權益	(74)	-0.2%	(40)	-0.1%	
歸屬於本公司業主之淨利	7,847	20.1%	4,302	11.2%	82%
EBITDA	11,522	29.5%	12,206	31.7%	-6%

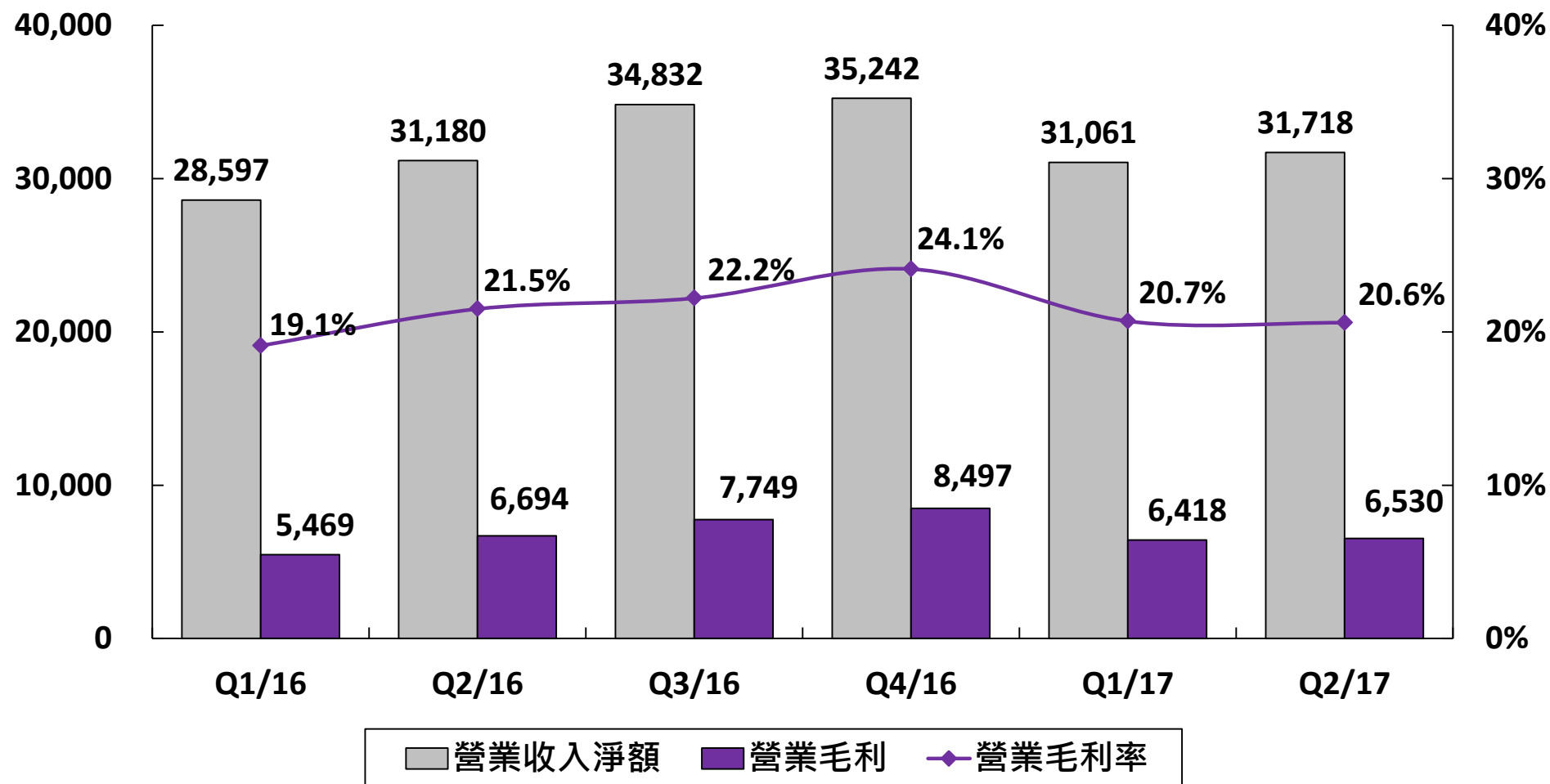


封裝業務

(未經會計師查核)



新台幣百萬元

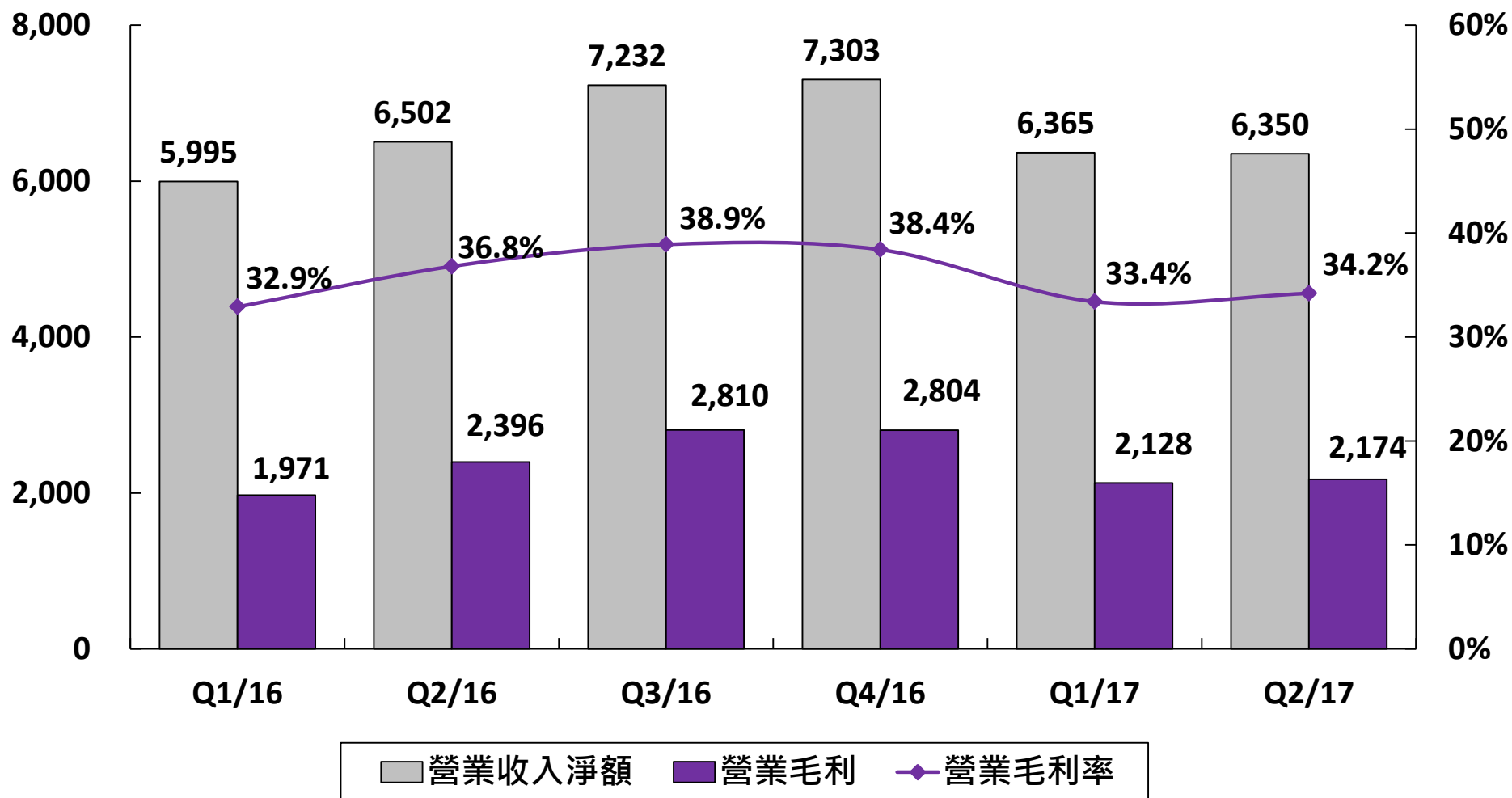


測試業務

(未經會計師查核)



新台幣百萬元

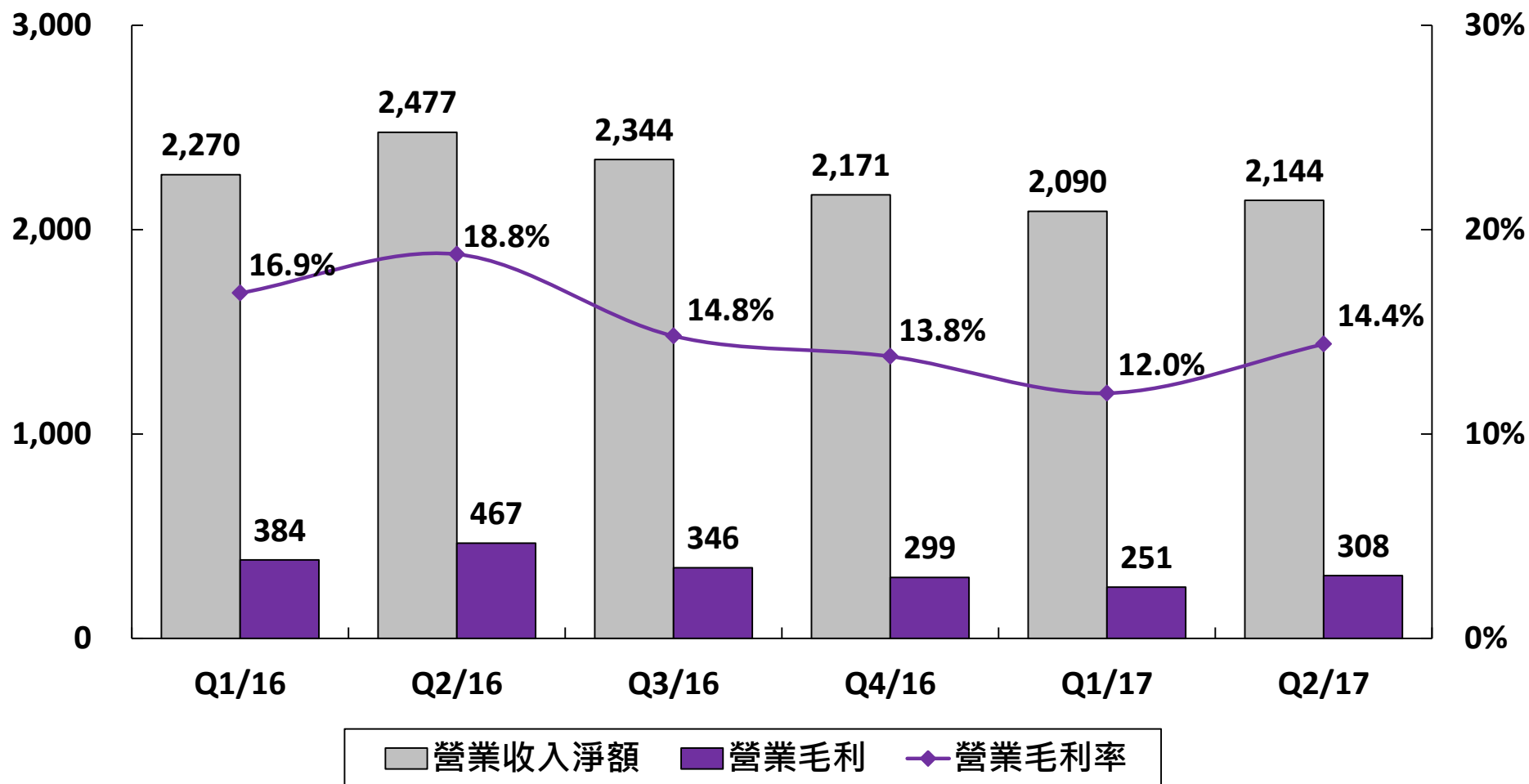


材料業務

(未經會計師查核)



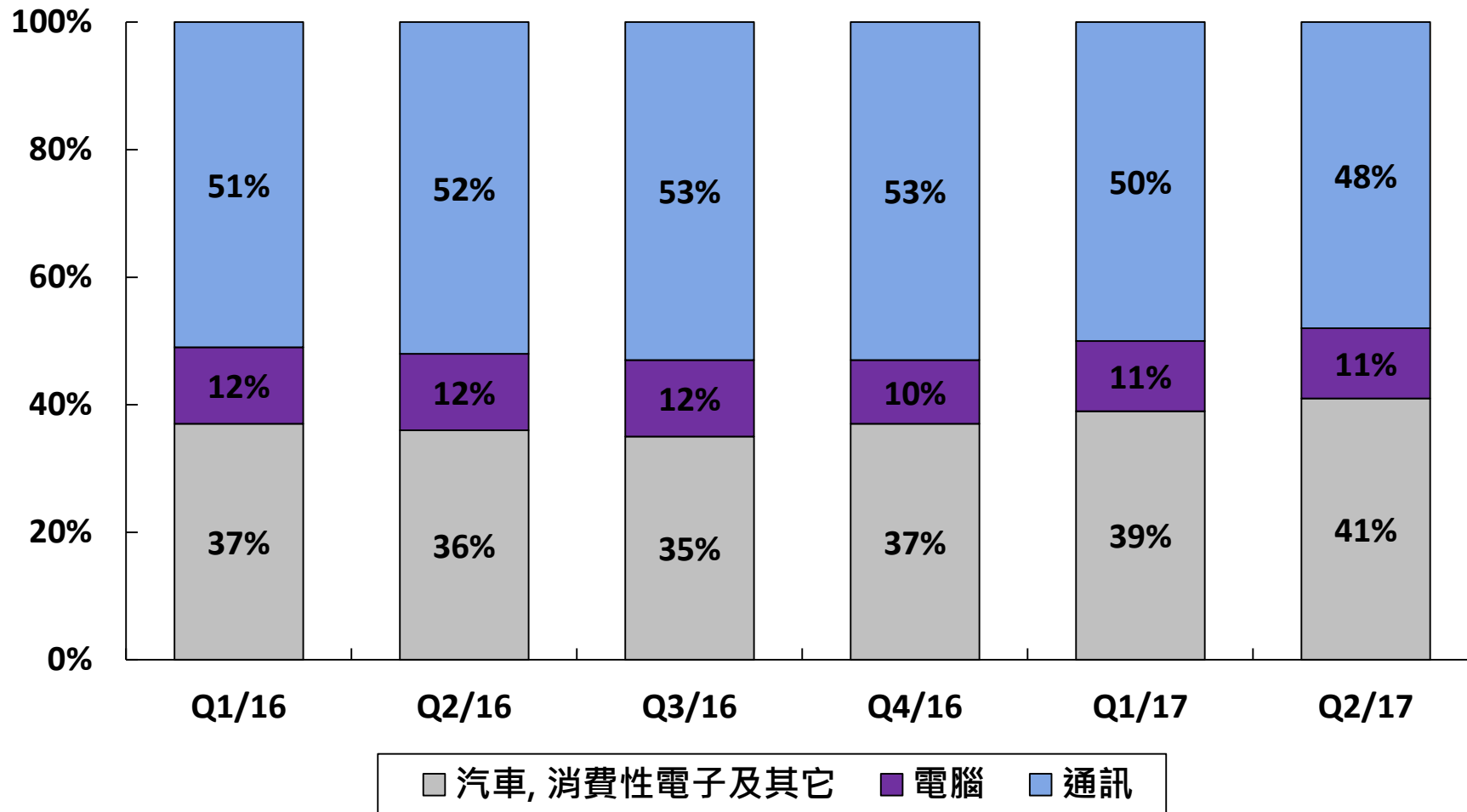
新台幣百萬元



半導體封測營收

產品應用別佔比

(未經會計師查核)

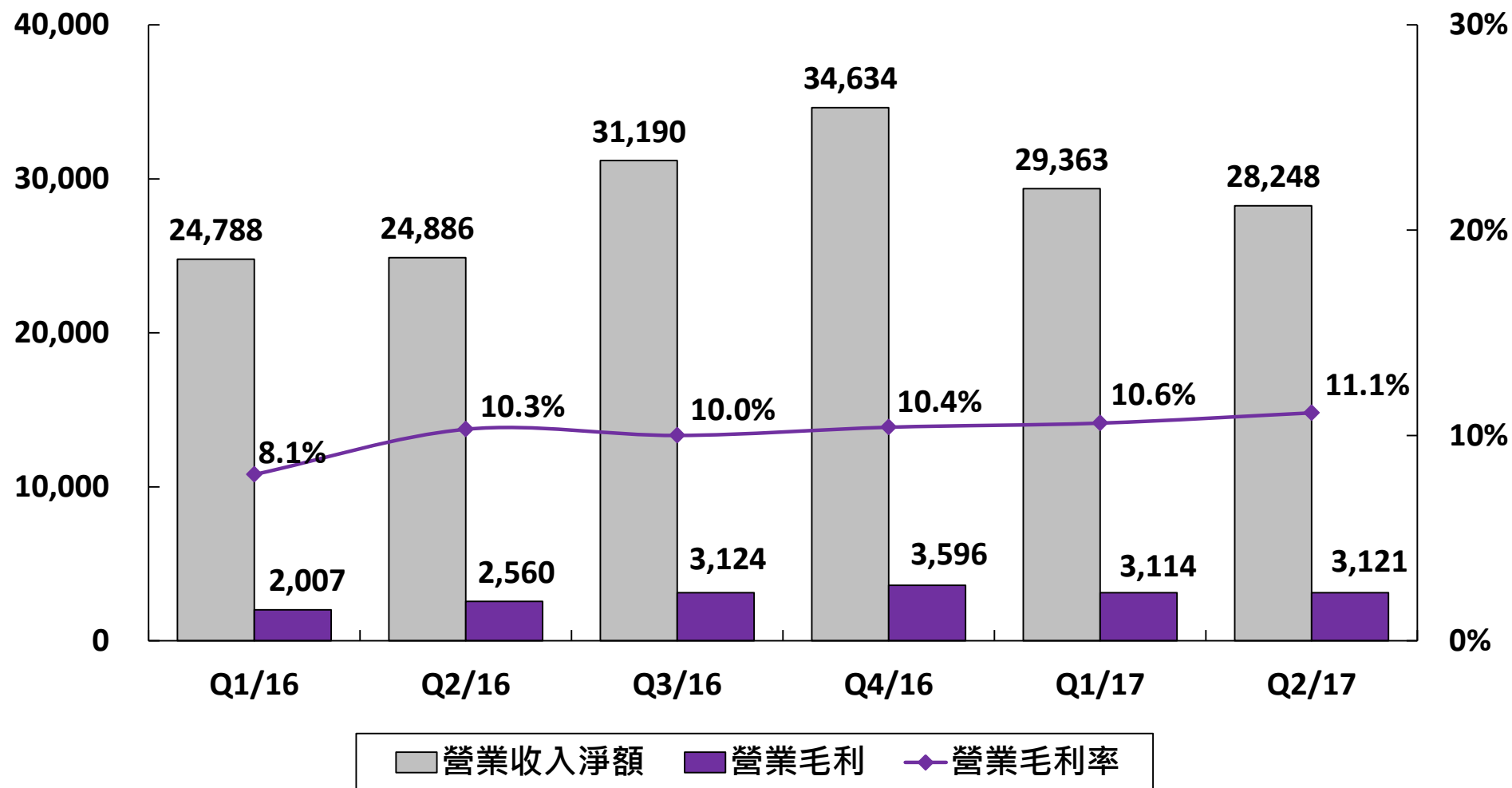


電子代工服務業務

(未經會計師查核)



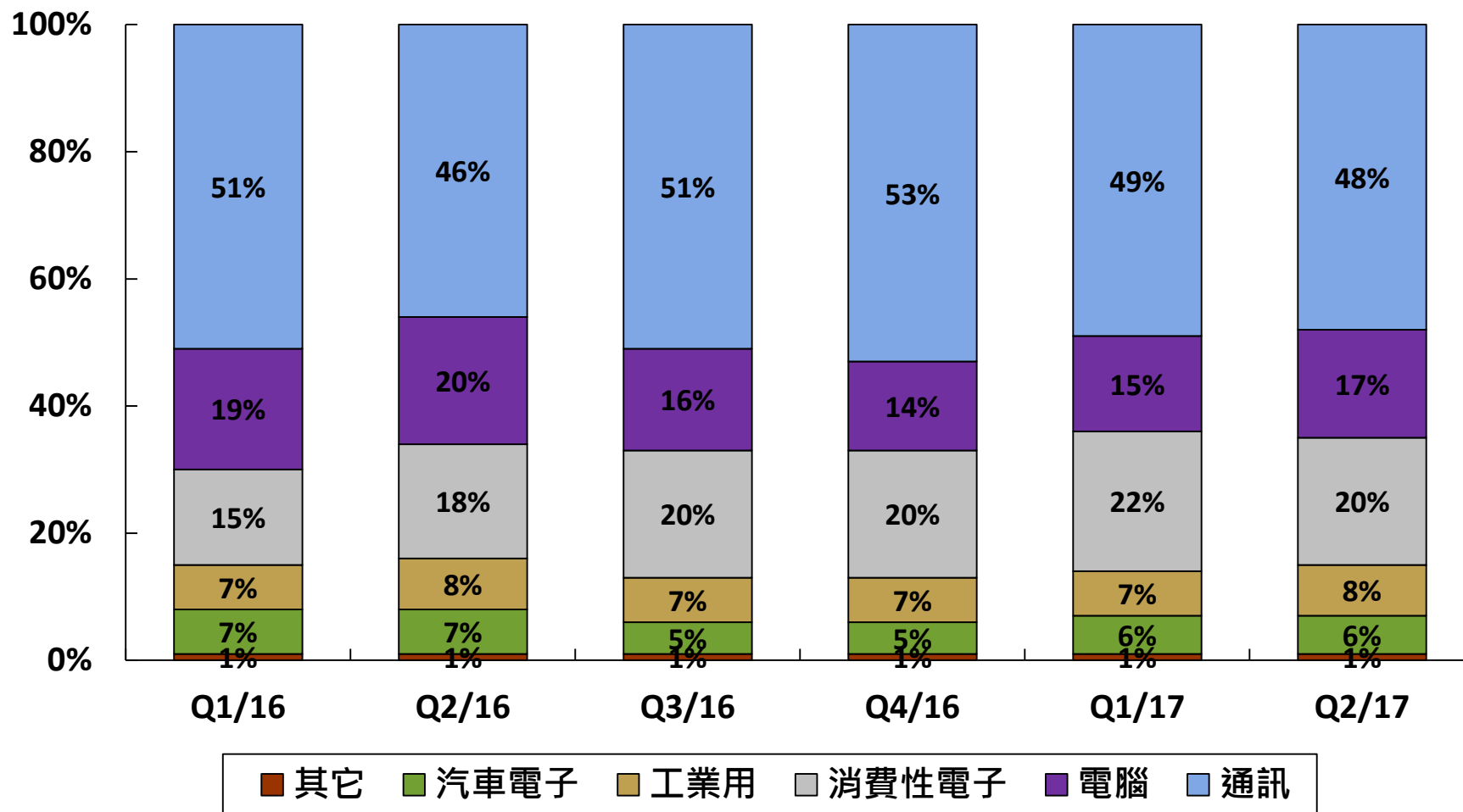
新台幣百萬元



電子代工服務業務

產品應用別

(未經會計師查核)



重要資產負債表項目及財務指標

(未經會計師查核)



(新台幣百萬元)	2017年6月30日	2017年3月31日	季變化
現金及約當現金	43,891	42,474	3.3%
金融資產 - 流動	4,138	3,720	11.2%
金融資產 - 非流動及採用權益法之投資	50,878	52,183	-2.5%
不動產、廠房及設備	140,378	140,072	0.2%
資產總計	356,623	347,517	2.6%
短期借款及應付短期票券	14,209	13,400	6.0%
一年內到期之應付公司債	15,236	15,179	0.4%
一年內到期之長期借款及應付租賃款	7,454	7,218	3.3%
應付公司債	25,845	28,476	-9.2%
長期借款及應付租賃款	28,823	33,639	-14.3%
權益總計 (含非控制權益)	179,063	176,758	1.3%
當季 EBITDA	19,085	11,764	62.2%
流動比率	1.30	1.38	
負債權益比率	0.24	0.29	

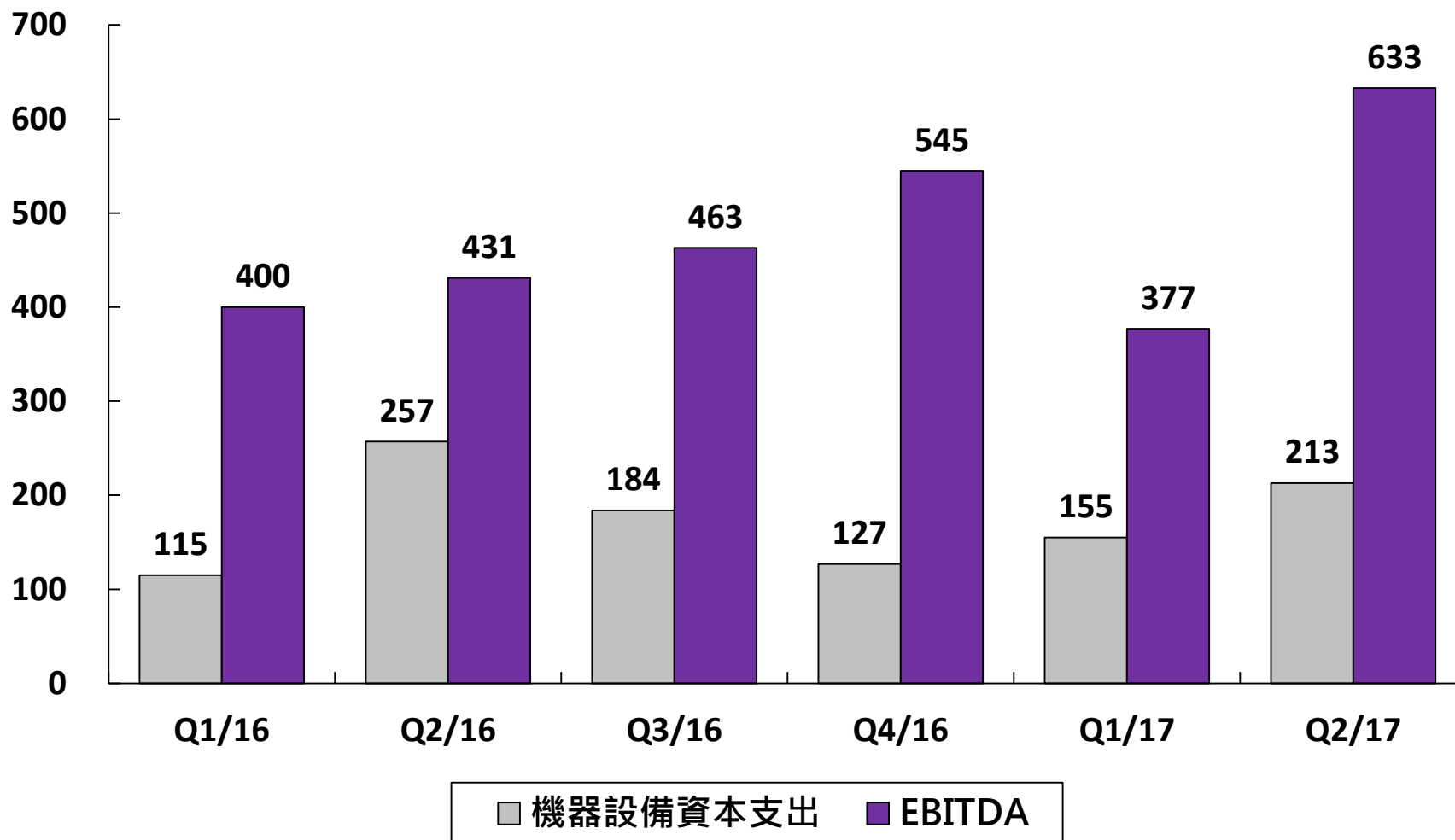


機器設備資本支出及EBITDA

(未經會計師查核)



美金百萬元



2017年第三季業績展望



根據對當前業務狀況的評估及匯率的假設，日月光公司2017年第三季的業績展望如下：

- 半導體封測事業第三季生意量將小幅低於去年第三季水準；
- 半導體封測事業第三季毛利率將相當於去年第二季水準；
- 電子代工服務第三季生意量將相當於去年第三季與第四季之平均；
- 電子代工服務毛利率將相當於去年第一季與第二季之平均。



Thank You

www.aseglobal.com
ir@aseglobal.com

